



P.C.B TERMINAL POSITION

JF-00155

NO	Description	Material	Qty	Plating	Specifications	PJ-008-SMD
1	Housing	PA46+30%Fiber	1	94V-0	Rating: DC 30V 0.5A	TITLE: PHONE JACK
2	Spring	t0.2 Cu-Ti Alloy	4	Ag-Plating	Contact Resistance: 30m ohm max	UNLESS OTHERWISE SPECIFIED TOLERANCE ±0.1 ANGLE TOL ±30° UNIT: mm SCALE: NA DRAWN: xing DATE: 2004-08-19 CHECKED: DATE: APPROVED: DATE:
3					Insulation Resistance: 100M ohm at 500V	
4					Dielectric Strength: AC 500V for 1 Minute	
5					Insertion & Extraction Force: 6-2.0kgf	
6					Life: 5.000 Cycles	
					Taping: 1.000 Pcs	
XYFWCN(www.xyfwcn.com)						